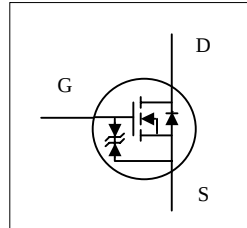
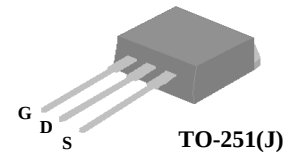




- ▼ 100% Avalanche Test
- ▼ ESD Improved Capability
- ▼ Simple Drive Requirement



BV_{DSS}	700V
$R_{DS(ON)}$	7Ω
I_D	1.6A



Description

AP02N70 from APEC provide the designer with the best combination of fast switching , low on-resistance and cost-effectiveness.

The TO-251 package is widely preferred for commercial-industrial through hole applications and suited for AC/DC converters.

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	700	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_C=25^\circ C$	Continuous Drain Current, V_{GS} @ 10V	1.6	A
$I_D@T_C=100^\circ C$	Continuous Drain Current, V_{GS} @ 10V	1	A
I_{DM}	Pulsed Drain Current ¹	6.4	A
$P_D@T_C=25^\circ C$	Total Power Dissipation	45	W
E_{AS}	Single Pulse Avalanche Energy ²	13	mJ
I_{AR}	Avalanche Current	1.6	A
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$

Thermal Data

Symbol	Parameter	Value	Units
Rthj-c	Maximum Thermal Resistance, Junction-case	2.8	$^\circ C/W$
Rthj-a	Maximum Thermal Resistance, Junction-ambient	110	$^\circ C/W$

Electrical Characteristics@T_j=25°C(unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =1mA	700	-	-	V
R _{DS(ON)}	Static Drain-Source On-Resistance ³	V _{GS} =10V, I _D =0.8A	-	-	7	Ω
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	2	-	4	V
g _{fs}	Forward Transconductance	V _{DS} =10V, I _D =0.8A	-	0.65	-	S
I _{DSS}	Drain-Source Leakage Current	V _{DS} =600V, V _{GS} =0V	-	-	10	uA
	Drain-Source Leakage Current (T _j =150°C)	V _{DS} =480V, V _{GS} =0V	-	-	100	uA
I _{GSS}	Gate-Source Leakage	V _{GS} =±20V	-	-	±10	uA
Q _g	Total Gate Charge ³	I _D =0.8A	-	17	30	nC
Q _{gs}	Gate-Source Charge	V _{DS} =560V	-	1.5	-	nC
Q _{gd}	Gate-Drain ("Miller") Charge	V _{GS} =10V	-	11	-	nC
t _{d(on)}	Turn-on Delay Time ³	V _{DD} =350V	-	10	-	ns
t _r	Rise Time	I _D =0.8A	-	8	-	ns
t _{d(off)}	Turn-off Delay Time	R _G =4.7Ω, V _{GS} =10V	-	21	-	ns
t _f	Fall Time	R _D =438Ω	-	15	-	ns
C _{iss}	Input Capacitance	V _{GS} =0V	-	170	300	pF
C _{oss}	Output Capacitance	V _{DS} =25V	-	30	-	pF
C _{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	20	-	pF

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V _{SD}	Forward On Voltage ³	I _S =1.6A, V _{GS} =0V	-	-	1.5	V
t _{rr}	Reverse Recovery Time ³	I _S =1.6A, V _{GS} =0V,	-	340	-	ns
Q _{rr}	Reverse Recovery Charge	dI/dt=100A/μs	-	2550	-	nC

Notes:

- 1.Pulse width limited by Max. junction temperature.
- 2.Starting T_j=25°C , V_{DD}=50V , L=10mH , R_G=25Ω , I_{AS}=1.6A.
- 3.Pulse test

THIS PRODUCT IS AN ELECTROSTATIC SENSITIVE, PLEASE HANDLE WITH CAUTION.

THIS PRODUCT HAS BEEN QUALIFIED FOR CONSUMER MARKET. APPLICATIONS OR USES AS CRITERIAL COMPONENT IN LIFE SUPPORT DEVICE OR SYSTEM ARE NOT AUTHORIZED.

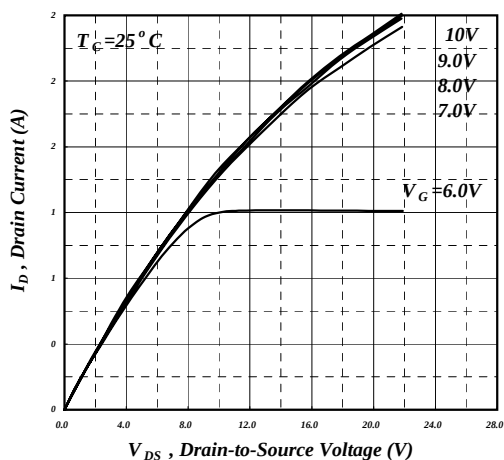


Fig 1. Typical Output Characteristics

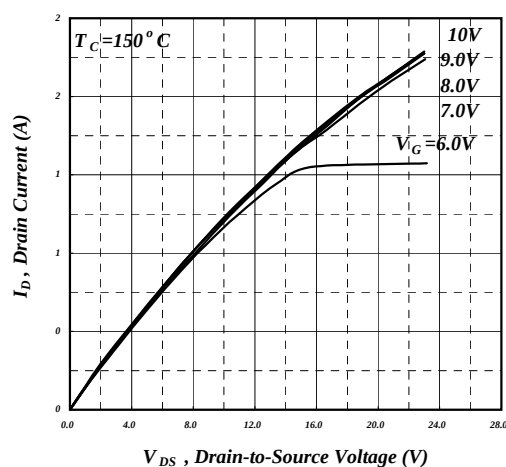


Fig 2. Typical Output Characteristics

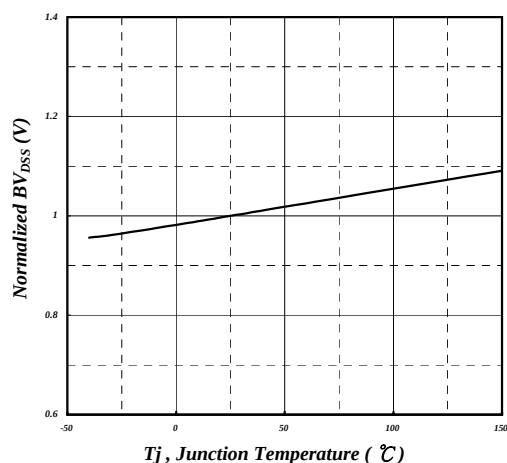
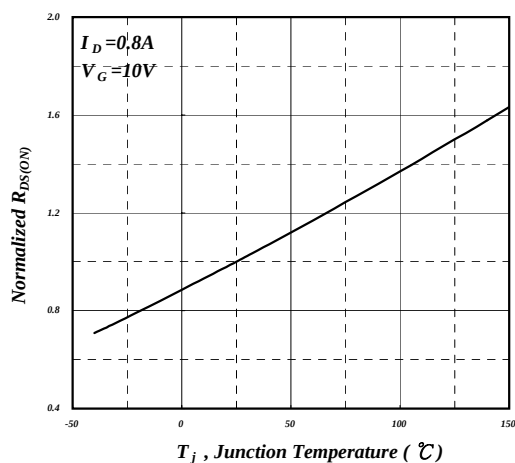
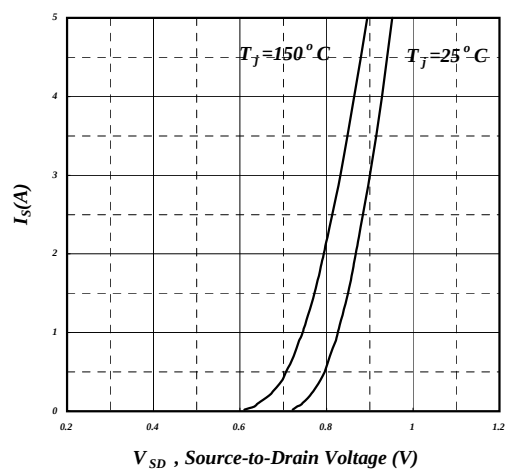
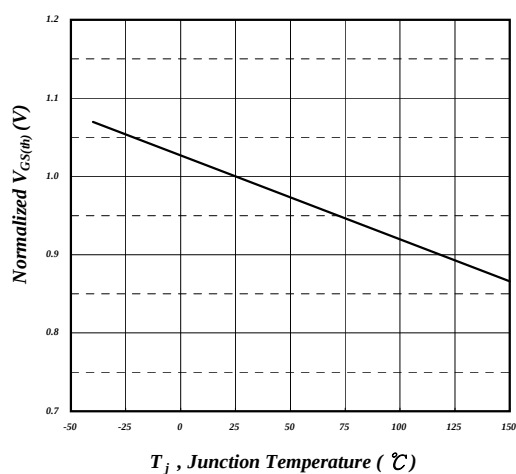


Fig 3. On-Resistance v.s. Gate Voltage

Fig 4. Normalized On-Resistance
v.s. Junction TemperatureFig 5. Forward Characteristic of
Reverse DiodeFig 6. Gate Threshold Voltage v.s.
Junction Temperature

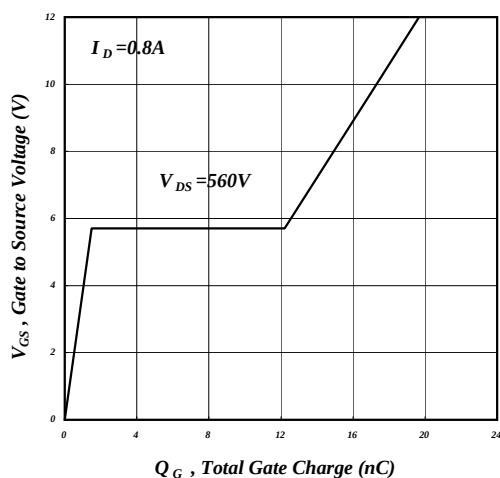


Fig 7. Gate Charge Characteristics

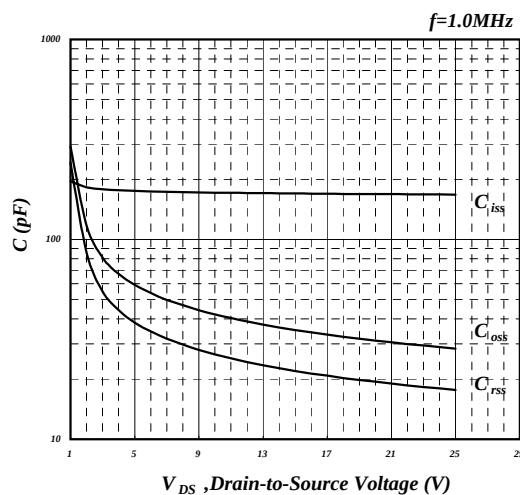


Fig 8. Typical Capacitance Characteristics

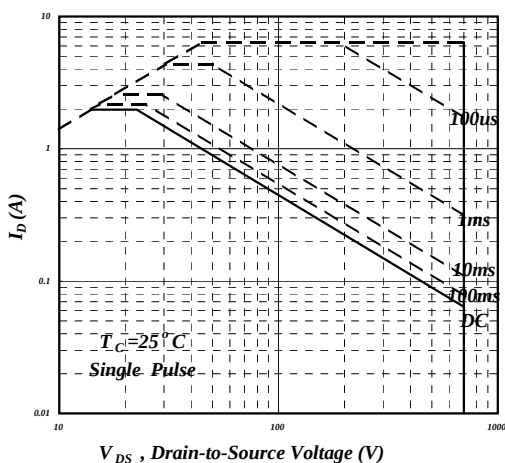


Fig 9. Maximum Safe Operating Area

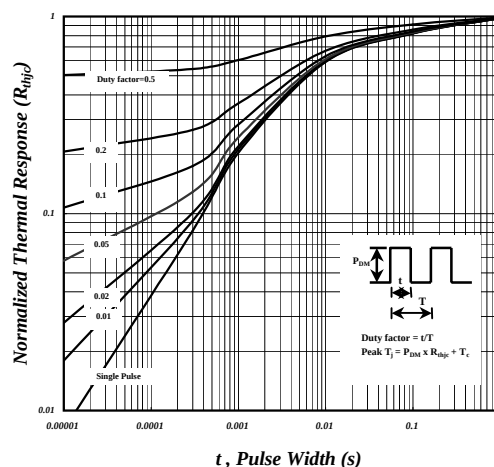


Fig 10. Effective Transient Thermal Impedance

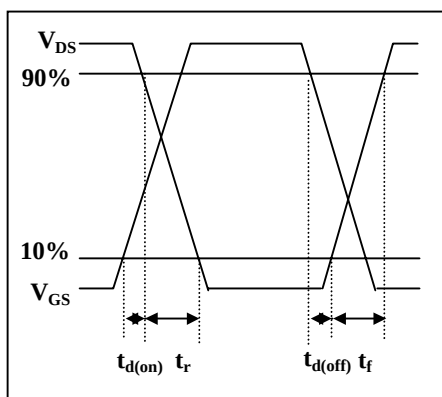


Fig 11. Switching Time Waveform

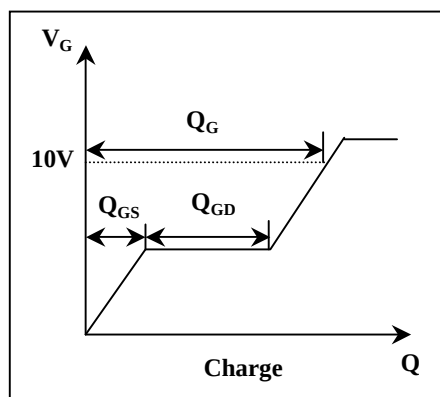
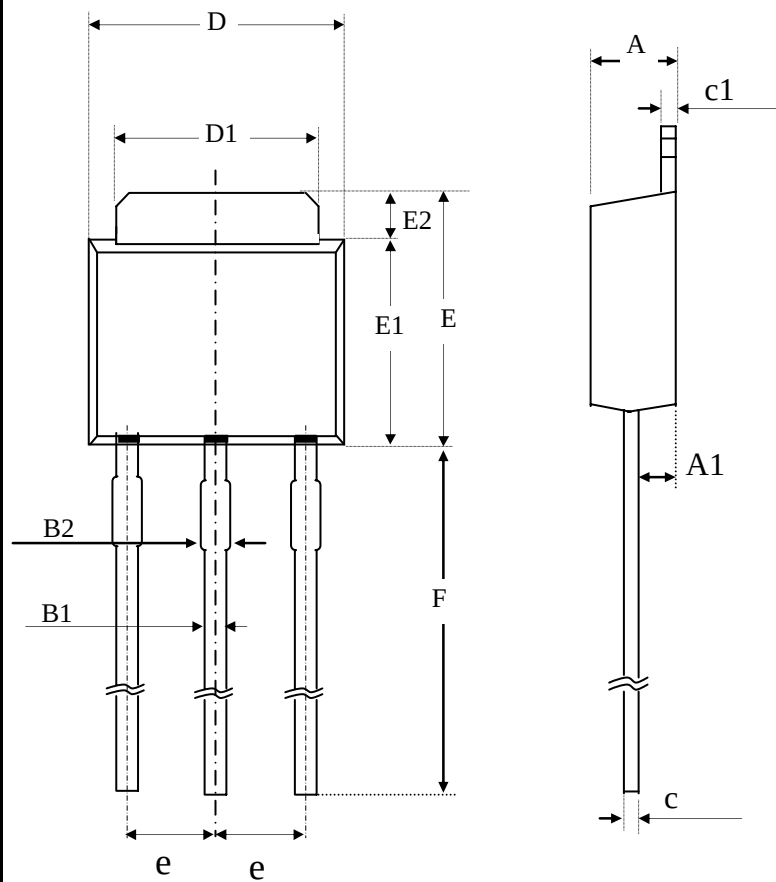


Fig 12. Gate Charge Waveform



SYMBOLS	Millimeters		
	MIN	NOM	MAX
	Original	Original	Original
A	2.10	2.30	2.50
A1	0.60	1.20	1.80
B1	0.40	0.60	0.80
B2	0.60	0.95	1.25
c	0.40	0.50	0.65
c1	0.40	0.55	0.70
D	6.00	6.50	7.00
D1	4.80	5.40	5.90
E1	5.00	5.50	6.00
E2	1.20	1.70	2.20
e	----	2.30	----
F	7.00	---	16.70

1.All Dimensions Are in Millimeters.

2.Dimension Does Not Include Mold Protrusions.

Part Marking Information & Packing : TO-251

